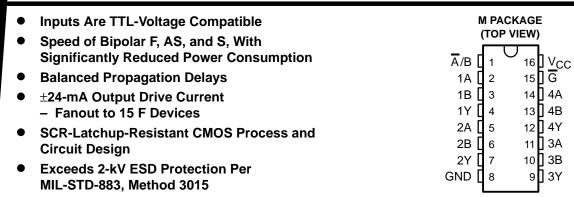
CD74ACT158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER

SCHS341 - MARCH 2003



description/ordering information

This quadruple 2-line to 1-line data selector/multiplexer is designed for 4.5-V to 5.5-V V_{CC} operation.

The CD74ACT158 features a common strobe (\overline{G}) input. When the strobe is high, all outputs are high. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. This device provides inverted data.

ORDERING INFORMATION

TA	PACKA	\GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
−55°C to 125°C	SOIC – M	Tape and reel	CD74ACT158M96	ACT158M

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each data selector/multiplexer)

	OUTPUT			
G	A/B	Α	В	Υ
Н	Х	Χ	Х	Н
L	L	L	X	Н
L	L	Н	X	L
L	Н	Χ	L	Н
L	Н	Χ	Н	L

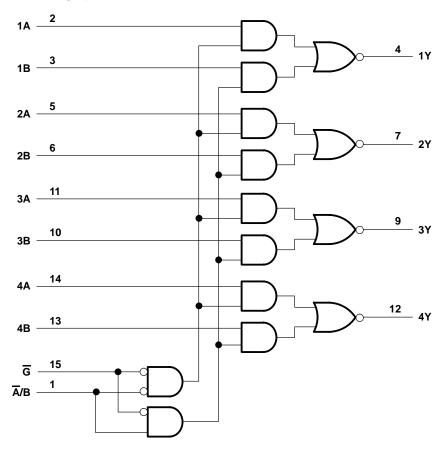


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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 6 V
Input clamp current, I _{IK} (V _I < 0 V or V _I > V _{CC}) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0 \text{ V or } V_O > V_{CC}$) (see Note 1)	±50 mA
Continuous output current, I_O ($V_O > 0$ V or $V_O < V_{CC}$)	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 2)	
Storage temperature range, T _{stq}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

		T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		0.8		0.8	V
٧I	Input voltage	0	VCC	0	VCC	0	Vcc	V
٧o	Output voltage	0	VCC	0	VCC	0	Vcc	V
IOH	High-level output current		-24		-24		-24	mA
loL	Low-level output current		24		24		24	mA
Δt/Δν	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vcc	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT
				MIN MAX		MIN	MAX	MIN	MAX	
		ΙΟΗ = -50 μΑ	4.5 V	4.4		4.4		4.4		
V	\\. = \\ or \\.	$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8		٧
VOH	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85				
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3.85		
		I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1	
V	VI = VIH or VIL	I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44	V
VOL		I _{OL} = 50 mA [†]	5.5 V				1.65			l v l
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65	
lį	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μΑ
Δl _{CC} ‡	$V_{I} = V_{CC} - 2.1 \text{ V}$		4.5 V to 5.5 V		2.4		3		2.8	mA
Ci					10		10		10	pF

Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C. Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
A or B	0.37
G	0.83
Ā/B	1.33

Unit Load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).



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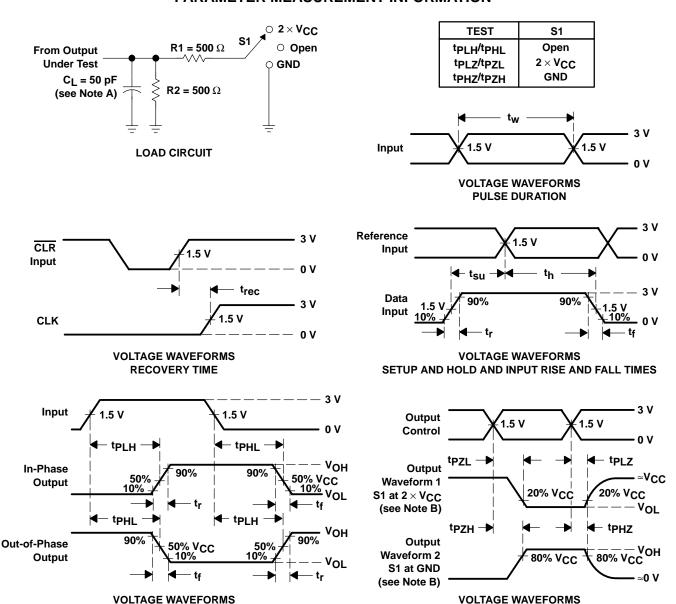
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40°0 85°	UNIT	
	(1141 01)	(6611 61)	MIN	MAX	MIN	MAX	
tPLH	A or B	Any Y	2.3	9.2	2.4	8.4	
^t PHL	AUB	Ally 1	2.3	9.2	2.4	8.4	ns
^t PLH	Ā/B	Any Y	3.4	13.5	3.6	12.3	ns
^t PHL	A/B	Ally I	3.4	13.5	3.6	12.3	115
^t PLH	G	Any V	3.1	12.4	3.3	11.3	
^t PHL	9	Any Y	3.1	12.4	3.3	11.3	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER			
C _{pd}	Power dissipation capacitance	149	pF	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$. Phase relationships between waveforms are arbitrary.

OUTPUT ENABLE AND DISABLE TIMES

- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tpz and tpzH are the same as ten.
- H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

1-Jul-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD74ACT158M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT158M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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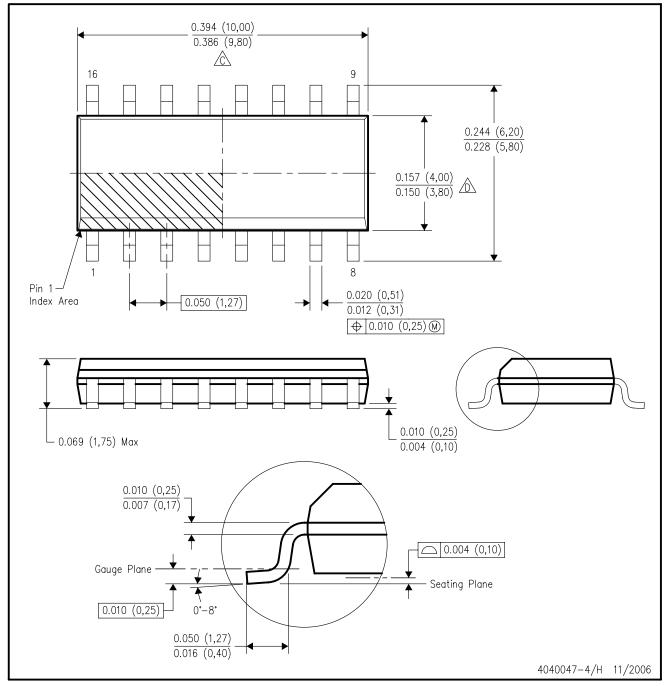
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



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